Reference

IEC 60068-2-21:2021
IEC TR 60068-3-12:2022
IEC 60068-3-13:2016
IEC TR 60068-3-15:2024
IEC TR 60068-3-82:2024
IEC 60194-1:2021
IEC 60194-2:2017
IEC 61188-5-2:2003
IEC 61188-5-3:2007
IEC 61188-5-4:2007
IEC 61188-5-5:2007
IEC 61188-5-6:2003
IEC 61188-5-8:2007
IEC 61188-6-1:2021
IEC 61188-6-2:2021
IEC 61188-6-4:2019
IEC 61188-7:2017
IEC TR 61188-8:2021
IEC 61189-2-501:2022
IEC 61189-2-630:2018
IEC 61189-2-719:2016
IEC 61189-2-720:2024
IEC 61189-2-721:2015
IEC 61189-2-801:2023
IEC 61189-2-803:2023
IEC 61189-2-804:2023
IEC 61189-2-805:2024
IEC 61189-2-807:2021
IEC 61189-2-808:2024
IEC TS 61189-3-301:2016
IEC 61189-3-719:2016
IEC 61189-3-913:2016
IEC TR 61189-3-914:2017
IEC 61189-5-1:2016
IEC 61189-5-2:2015
IEC 61189-5-3:2015
IEC 61189-5-4:2015
IEC 61189-5-301:2021
IEC 61189-5-501:2021
IEC 61189-5-502:2021
IEC 61189-5-503:2017
IEC 61189-5-504:2020
IEC TR 61189-5-506:2019
IEC 61189-5-601:2021
IEC 61189-11:2013
IEC 61190-1-1:2002

IEC 61190-1-2:2014
IEC 61190-1-3:2017
IEC 61191-1:2018 RLV
IEC 61191-1:2018
IEC 61191-2:2017
IEC 61191-2:2017/COR1:2019
IEC 61191-3:2017
IEC 61191-4:2017
IEC 61191-6:2010
IEC TR 61191-7:2020
IEC TR 61191-8:2021
IEC TR 61191-9:2023
IEC PAS 61191-10:2022
IEC 61193-1:2001
IEC 61193-2:2007
IEC 61193-3:2013
IEC 61249-2-1:2005
IEC 61249-2-2:2005
IEC 61249-2-4:2001
IEC 61249-2-5:2003
IEC 61249-2-6:2003
IEC 61249-2-7:2002
IEC 61249-2-8:2003
IEC 61249-2-9:2003
IEC 61249-2-10:2003
IEC 61249-2-11:2003
IEC 61249-2-12:1999
IEC 61249-2-13:1999
IEC 61249-2-21:2003
IEC 61249-2-22:2005
IEC 61249-2-23:2005
IEC 61249-2-26:2005
IEC 61249-2-27:2012
IEC 61249-2-30:2012
IEC 61249-2-31:2009
IEC 61249-2-32:2009
IEC 61249-2-33:2009
IEC 61249-2-34:2009
IEC 61249-2-35:2008
IEC 61249-2-36:2008
IEC 61249-2-37:2008
IEC 61249-2-38:2008
IEC 61249-2-39:2012
IEC 61249-2-40:2012
IEC 61249-2-41:2010
IEC 61249-2-42:2010
IEC 61249-2-43:2016

IEC 61249-2-44:2016
IEC 61249-2-45:2018
IEC 61249-2-46:2018
IEC 61249-2-47:2018
IEC 61249-2-51:2023
IEC 61249-3-3:1999
IEC 61249-3-4:1999
IEC 61249-3-5:1999
IEC 61249-4-1:2008
IEC 61249-4-2:2005
IEC 61249-4-5:2005
IEC 61249-4-11:2005
IEC 61249-4-12:2005
IEC 61249-4-14:2009
IEC 61249-4-15:2009
IEC 61249-4-16:2009
IEC 61249-4-17:2009
IEC 61249-4-18:2013
IEC 61249-4-19:2013
IEC 61249-5-1:1995
IEC 61249-5-4:1996
IEC 61249-6-3:2023
IEC 61249-7-1:1995
IEC 61249-8-7:1996
IEC 61249-8-8:1997
IEC 61445:2012
IEC 61523-1:2023
IEC 61523-3:2004
IEC 61523-4:2023
IEC 61523-4:2023/COR1:2024
IEC 61636:2021
IEC 61636-1:2021
IEC 61636-2:2023
IEC 61671:2012
IEC 61671-2:2016
IEC 61671-4:2016
IEC 61671-5:2016
IEC 61671-6:2016
IEC 61690-1:2000
IEC 61690-2:2000
IEC 61691-1-1:2023
IEC 61691-6:2021
IEC 61691-7:2009
IEC 61691-8:2021
IEC 61760-1:2020
IEC 61760-2:2021 RLV
IEC 61760-2:2021

IEC 61760-3:2021
IEC TR 61760-3-1:2022
IEC 61760-4:2015+AMD1:2018 CSV
IEC 61760-4:2015
IEC 61760-4:2015/AMD1:2018
IEC TR 61760-5-1:2024
IEC 61926-1:1999
IEC 62014-4:2015
IEC 62014-5:2015
IEC 62090:2017
IEC 62137-1-1:2007
IEC 62137-1-2:2007
IEC 62137-1-3:2008
IEC 62137-1-4:2009
IEC 62137-1-5:2009
IEC 62137-3:2011
IEC 62243:2012
IEC 62326-4:1996
IEC 62326-4-1:1996
IEC 62525:2007
IEC 62526:2007
IEC 62527:2007
IEC 62528:2007
IEC 62529:2024
IEC 62530:2021
IEC 62530-2:2023
IEC 62531:2012
IEC TR 62699-1:2014
IEC 62739-1:2013
IEC 62739-2:2016
IEC 62739-3:2017
IEC TR 62856:2013
IEC TR 62866:2014
IEC 62878-1:2019
IEC 62878-1-1:2015
IEC TS 62878-2-1:2015
IEC TR 62878-2-2:2015
IEC TS 62878-2-3:2015
IEC TS 62878-2-4:2015
IEC 62878-2-5:2019
IEC TR 62878-2-7:2019
IEC TR 62878-2-8:2021
IEC TR 62878-2-9:2022
IEC TS 62878-2-10:2024
IEC 62878-2-602:2021
IEC 63003:2015
IEC 63004:2015

IEC TR 63017:2015
IEC TR 63018:2015
IEC TR 63051:2017
IEC 63055:2023
IEC 63215-2:2023
IEC 63251:2023
IEC 63501-2416:2023
IEC 63504-2804:2023
IEC 60115-4-10:2023
IEC 60115-9:2003
IEC 60115-9-1:2003
IEC 60286-1:2017+AMD1:2021 CSV
IEC 60286-1:2017
IEC 60286-1:2017/AMD1:2021
IEC 60286-2:2022
IEC 60286-3:2022
IEC 60286-3:2022 CMV
IEC TR 60286-3-3:2021
IEC TR 60286-3-4:2021
IEC TR 60286-3-4:2021/COR1:2022
IEC 60286-4:2013
IEC 60286-5:2018
IEC 60286-5:2018 RLV
IEC 60286-6:2004
IEC TS 60286-6-1:2023
IEC TR 60286-7:2019
IEC 60301:2012
IEC 60384-1-1:2022
IEC 60384-3:2016
IEC 60384-3-1:2006
IEC 60384-4-2:2007
IEC 60384-9-1:2005
IEC 60384-11-1:2008
IEC 60384-14-2:2016
IEC 60384-15-1:1984
IEC 60384-15-2:1984
IEC 60384-16:2019
IEC 60384-16:2019/COR1:2020
IEC 60384-16-1:2005
IEC 60384-17:2019
IEC 60384-17:2019 RLV
IEC 60384-17:2019/COR1:2020
IEC 60384-18:2016
IEC 60384-18-1:2007
IEC 60384-18-2:2007
IEC 60384-19:2022
IEC 60384-20:2023 RLV

IEC 60384-20:2023
IEC 60384-21:2024
IEC 60384-21:2024 CMV
IEC 60384-21-1:2004
IEC 60384-21-1:2004/COR1:2004
IEC 60384-22-1:2004
IEC 60384-22-1:2004/COR1:2004
IEC 60384-23:2023 RLV
IEC 60384-23:2023
IEC 60384-24:2021 RLV
IEC 60384-24:2021
IEC 60384-24-1:2006
IEC 60384-25:2021
IEC 60384-25:2021 RLV
IEC 60384-25:2021/COR1:2023
IEC 60384-25-1:2006
IEC 60384-26:2018
IEC 60384-26:2018 RLV
IEC 60384-26:2018/COR1:2020
IEC 60384-26-1:2010
IEC 60393-3:2023
IEC 60393-4:2023
IEC 60393-5:2015
IEC 60393-6:2015
IEC 60539-1:2022
IEC 60539-2:2019
IEC 60539-2:2019 RLV
IEC 60717:2012
IEC 60738-1-2:2008
IEC 60738-1-3:2008
IEC 60738-1-4:2008
IEC 60915:2006
IEC 60915:2006/COR1:2007
IEC 60915:2006/COR2:2008
IEC 60938-2:2021
IEC 60938-2-1:2023
IEC 60939-2-1:2004
IEC 60939-2-2:2004
IEC 60939-3:2024 RLV
IEC 60939-3:2024
IEC 60940:2015
IEC 62319-1:2005
IEC 62319-1:2005/COR1:2009
IEC 62319-1-1:2005
IEC 62391-1:2022
IEC 62391-2:2006
IEC 62391-2-1:2006

IEC 62490-1:2010
IEC 62490-2:2010
IEC 62812:2019
IEC 62812:2019/COR1:2020
IEC 62813:2015
IEC TS 63337:2024
IEC TR 63362-1:2022
IEC 60749-1:2002
IEC 60749-1:2002/COR1:2003
IEC 60749-2:2002
IEC 60749-2:2002/COR1:2003
IEC 60749-3:2017
IEC 60749-4:2017
IEC 60749-5:2023
IEC 60749-5:2023 RLV
IEC 60749-6:2017
IEC 60749-7:2011
IEC 60749-8:2002
IEC 60749-8:2002/COR1:2003
IEC 60749-8:2002/COR2:2003
IEC 60749-9:2017
IEC 60749-10:2022
IEC 60749-11:2002
IEC 60749-11:2002/COR1:2003
IEC 60749-11:2002/COR2:2003
IEC 60749-12:2017
IEC 60749-13:2018
IEC 60749-14:2003
IEC 60749-15:2020 RLV
IEC 60749-15:2020
IEC 60749-16:2003
IEC 60749-17:2019
IEC 60749-18:2019
IEC 60749-18:2019 RLV
IEC 60749-19:2003+AMD1:2010 CSV
IEC 60749-19:2003
IEC 60749-19:2003/AMD1:2010
IEC 60749-20:2020
IEC 60749-20:2020 RLV
IEC 60749-20-1:2019
IEC 60749-20-1:2019 RLV
IEC 60749-21:2011
IEC 60749-22:2002
IEC 60749-22:2002/COR1:2003
IEC 60749-23:2004+AMD1:2011 CSV
IEC 60749-23:2004
IEC 60749-23:2004/AMD1:2011

IEC 60749-24:2004
IEC 60749-25:2003
IEC 60749-26:2018
IEC 60749-27:2006+AMD1:2012 CSV
IEC 60749-27:2006
IEC 60749-27:2006/AMD1:2012
IEC 60749-28:2022
IEC 60749-28:2022 RLV
IEC 60749-29:2011
IEC 60749-30:2020
IEC 60749-30:2020 RLV
IEC 60749-31:2002
IEC 60749-31:2002/COR1:2003
IEC 60749-32:2002+AMD1:2010 CSV
IEC 60749-32:2002
IEC 60749-32:2002/COR1:2003
IEC 60749-32:2002/AMD1:2010
IEC 60749-33:2004
IEC 60749-34:2010
IEC 60749-35:2006
IEC 60749-36:2003
IEC 60749-37:2022
IEC 60749-37:2022 RLV
IEC 60749-38:2008
IEC 60749-39:2021 RLV
IEC 60749-39:2021
IEC 60749-40:2011
IEC 60749-41:2020
IEC 60749-42:2014
IEC 60749-44:2016
IEC 62047-28:2017
IEC 62258-1:2009
IEC 62258-2:2011
IEC TR 62258-3:2010
IEC TR 62258-4:2012
IEC 62258-5:2006
IEC 62258-6:2006
IEC TR 62258-7:2007
IEC TR 62258-8:2008
IEC 62373:2006
IEC 62373-1:2020
IEC 62374:2007
IEC 62374-1:2010
IEC 62415:2010
IEC 62416:2010
IEC 62417:2010
IEC 62418:2010

IEC 62435-1:2017
IEC 62435-2:2017
IEC 62435-3:2020
IEC 62435-4:2018
IEC 62435-5:2017
IEC 62435-6:2018
IEC 62435-7:2020
IEC 62435-8:2020
IEC 62435-9:2021
IEC 62483:2013
IEC 62615:2010
IEC 62779-1:2016
IEC 62779-2:2016
IEC 62779-3:2016
IEC 62779-4:2020
IEC 62830-1:2017
IEC 62830-2:2017
IEC 62830-3:2017
IEC 62830-4:2019
IEC 62830-5:2021
IEC 62830-6:2019
IEC 62830-7:2021
IEC 62830-8:2021
IEC 62880-1:2017
IEC 62951-1:2017
IEC 62951-2:2019
IEC 62951-3:2018
IEC 62951-4:2019
IEC 62951-5:2019
IEC 62951-6:2019
IEC 62951-7:2019
IEC 62951-8:2023
IEC 62951-9:2022
IEC 62969-1:2017
IEC 62969-2:2018
IEC 62969-3:2018
IEC 62969-4:2018
IEC 63068-1:2019
IEC 63068-2:2019
IEC 63068-3:2020
IEC 63068-4:2022
IEC TR 63133:2017
IEC 63150-1:2019
IEC 63229:2021
IEC 63244-1:2021
IEC 63275-1:2022
IEC 63275-2:2022

IEC 63284:2022
IEC 63287-1:2021
IEC 63287-2:2023
IEC TR 63357:2022
IEC 63364-1:2022
IEC 63373:2022
IEC 62047-1:2016
IEC 62047-2:2006
IEC 62047-3:2006
IEC 62047-4:2008
IEC 62047-5:2011
IEC 62047-5:2011/COR1:2012
IEC 62047-6:2009
IEC 62047-7:2011
IEC 62047-8:2011
IEC 62047-9:2011
IEC 62047-9:2011/COR1:2012
IEC 62047-10:2011
IEC 62047-10:2011/COR1:2012
IEC 62047-11:2013
IEC 62047-12:2011
IEC 62047-13:2012
IEC 62047-14:2012
IEC 62047-16:2015
IEC 62047-17:2015
IEC 62047-18:2013
IEC 62047-19:2013
IEC 62047-20:2014
IEC 62047-21:2014
IEC 62047-22:2014
IEC 62047-25:2016
IEC 62047-26:2016
IEC 62047-27:2017
IEC 62047-29:2017
IEC 62047-30:2017
IEC 62047-31:2019
IEC 62047-32:2019
IEC 62047-33:2019
IEC 62047-34:2019
IEC 62047-35:2019
IEC 62047-36:2019
IEC 62047-37:2020
IEC 62047-38:2021
IEC 62047-40:2021
IEC 62047-41:2021
IEC 62047-42:2022
IEC 62047-43:2024

IEC 62047-44:2024
IEC 62047-47:2024
IEC 62047-48:2024
IEC 60747-4:2007+AMD1:2017 CSV
IEC 60747-4:2007
IEC 60747-4:2007/AMD1:2017
IEC 60747-5-4:2022
IEC 60747-5-5:2020
IEC 60747-5-6:2021 RLV
IEC 60747-5-6:2021
IEC 60747-5-7:2016
IEC 60747-5-8:2019
IEC 60747-5-9:2019
IEC 60747-5-10:2019
IEC 60747-5-11:2019
IEC TR 60747-5-12:2021
IEC 60747-5-13:2021
IEC 60747-5-14:2022
IEC 60747-5-15:2022
IEC 60747-5-16:2023
IEC 60747-6:2016
IEC 60747-9:2019
IEC 60747-14-1:2010
IEC 60747-14-2:2000
IEC 60747-14-3:2009
IEC 60747-14-4:2011
IEC 60747-14-5:2010
IEC 60747-14-10:2019
IEC 60747-14-11:2021
IEC 60747-15:2010
IEC 60747-16-1:2001+AMD1:2007+AMD2:2017 CSV
IEC 60747-16-1:2001+AMD1:2007 CSV
IEC 60747-16-1:2001
IEC 60747-16-1:2001/AMD1:2007
IEC 60747-16-1:2001/AMD2:2017
IEC 60747-16-2:2001+AMD1:2007 CSV
IEC 60747-16-2:2001
IEC 60747-16-2:2001/AMD1:2007
IEC 60747-16-3:2002+AMD1:2009+AMD2:2017 CSV
IEC 60747-16-3:2002+AMD1:2009 CSV
IEC 60747-16-3:2002
IEC 60747-16-3:2002/AMD1:2009
IEC 60747-16-3:2002/AMD2:2017
IEC 60747-16-4:2004+AMD1:2009+AMD2:2017 CSV
IEC 60747-16-4:2004+AMD1:2009 CSV
IEC 60747-16-4:2004
IEC 60747-16-4:2004/AMD1:2009

IEC 60747-16-4:2004/AMD2:2017
IEC 60747-16-5:2013+AMD1:2020 CSV
IEC 60747-16-5:2013
IEC 60747-16-5:2013/AMD1:2020
IEC 60747-16-5:2013/AMD1:2020/COR1:2020
IEC 60747-16-6:2019
IEC 60747-16-7:2022
IEC 60747-16-8:2022
IEC 60747-16-9:2024
IEC 60747-16-10:2004
IEC 60747-17:2020
IEC 60747-17:2020/COR1:2021
IEC 60747-18-1:2019
IEC 60747-18-2:2020
IEC 60747-18-3:2019
IEC 60747-18-4:2023
IEC 60747-18-5:2023
IEC 60747-19-1:2019
IEC TS 60747-19-2:2021
IEC 60191-2:2012 DB
IEC 60191-2:1966
IEC 60191-2:1966/AMD1:2001
IEC 60191-2:1966/AMD2:2001
IEC 60191-2:1966/AMD3:2001
IEC 60191-2:1966/AMD4:2001
IEC 60191-2:1966/AMD5:2002
IEC 60191-2:1966/AMD6:2002
IEC 60191-2:1966/AMD7:2002
IEC 60191-2:1966/AMD8:2003
IEC 60191-2:1966/AMD9:2003
IEC 60191-2:1966/AMD10:2004
IEC 60191-2:1966/AMD11:2004
IEC 60191-2:1966/AMD12:2006
IEC 60191-2:1966/AMD13:2006
IEC 60191-2:1966/AMD14:2006
IEC 60191-2:1966/AMD15:2006
IEC 60191-2:1966/AMD16:2007
IEC 60191-2:1966/AMD17:2008
IEC 60191-2:1966/AMD18:2011
IEC 60191-2:1966/AMD19:2012
IEC 60191-2:1966/AMD20:2018
IEC 60191-2:1966/AMD21:2020
IEC 60191-3:1999
IEC 60191-4:2013+AMD1:2018 CSV
IEC 60191-4:2013
IEC 60191-4:2013/AMD1:2018
IEC 60191-5:1997

IEC 60191-6:2009
IEC 60191-6-1:2001
IEC 60191-6-2:2001
IEC 60191-6-2:2001/COR1:2002
IEC 60191-6-3:2000
IEC 60191-6-4:2003
IEC 60191-6-5:2001
IEC 60191-6-6:2001
IEC 60191-6-8:2001
IEC 60191-6-10:2003
IEC 60191-6-12:2011
IEC 60191-6-13:2016
IEC 60191-6-16:2007
IEC 60191-6-17:2011
IEC 60191-6-18:2010
IEC 60191-6-18:2010/COR1:2010
IEC 60191-6-18:2010/COR2:2010
IEC 60191-6-19:2010
IEC 60191-6-20:2010
IEC 60191-6-21:2010
IEC 60191-6-22:2012
IEC 60191-2T:1996
IEC 60191-2U:1997
IEC 60191-2V:1998
IEC 60191-2W:1999
IEC 60191-2X:1999
IEC 60191-2X:1999/COR1:2000
IEC 60191-2Y:2000
IEC 60191-2Z:2000
IEC TR 63378-1:2021
IEC 60748-2-2:1992
IEC 60748-2-2:1992/AMD1:1994
IEC 60748-2-5:1992
IEC 60748-2-6:1991
IEC 60748-2-7:1992
IEC 60748-2-8:1993
IEC 60748-2-9:1994
IEC 60748-2-10:1994
IEC 60748-2-11:1999
IEC 60748-2-12:2001
IEC 60748-2-20:2008
IEC 60748-4:1997
IEC 60748-4-1:1993
IEC 60748-4-2:1993
IEC 60748-4-3:2006
IEC 60748-5:1997
IEC 60748-11:1990

IEC 60748-11:1990/AMD1:1995
IEC 60748-11:1990/AMD2:1999
IEC 60748-11-1:1992
IEC 60748-20-1:1994
IEC 60748-23-1:2002
IEC 60748-23-2:2002
IEC 60748-23-3:2002
IEC 60748-23-4:2002
IEC 60748-23-5:2003
IEC 61739:1996
IEC 61943:1999
IEC TS 61944:2000
IEC TS 61945:2000
IEC 61964:1999
IEC 61967-1:2018 RLV
IEC 61967-1:2018
IEC TR 61967-1-1:2015
IEC 61967-2:2005
IEC TS 61967-3:2014
IEC 61967-4:2021 RLV
IEC 61967-4:2021
IEC TR 61967-4-1:2005
IEC 61967-5:2003
IEC 61967-6:2002+AMD1:2008 CSV
IEC 61967-6:2002
IEC 61967-6:2002/COR1:2010
IEC 61967-6:2002/AMD1:2008
IEC 61967-8:2023
IEC 61967-8:2023 RLV
IEC 62132-1:2015
IEC 62132-2:2010
IEC 62132-4:2006
IEC 62132-5:2005
IEC 62132-8:2012
IEC TS 62132-9:2014
IEC TS 62215-2:2007
IEC 62215-3:2013
IEC 62228-1:2018
IEC 62228-2:2016
IEC 62228-3:2019
IEC 62228-3:2019/COR1:2023
IEC 62228-5:2021
IEC 62228-6:2022
IEC 62228-7:2022
IEC TS 62404:2007
IEC 62433-1:2019
IEC 62433-1:2019/COR1:2020

IEC 62433-2:2017
IEC TR 62433-2-1:2010
IEC 62433-3:2017
IEC 62433-4:2016
IEC 62433-6:2020
IEC 63011-1:2018
IEC 63011-2:2018
IEC 63011-3:2018

Title

Environmental testing - Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices
Environmental testing - Part 3-12: Supporting documentation and guidance - Method to evaluate a possible lead-fr
Environmental testing - Part 3-13: Supporting documentation and guidance on Test T - Soldering
Environmental testing - Part 3-15: Supporting documentation and guidance - Vacuum-assisted reflow soldering
Environmental testing - Part 3-82: Supporting documentation and guidance - Confirmation of the performance of v
Printed boards design, manufacture and assembly - Vocabulary - Part 1: Common usage in printed board and electr
Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies a
Printed boards and printed board assemblies - Design and use - Part 5-2: Attachment (land/joint) considerations - D
Printed boards and printed board assemblies - Design and use - Part 5-3: Attachment (land/joint) considerations - C
Printed boards and printed board assemblies - Design and use - Part 5-4: Attachment (land/joint) considerations - C
Printed boards and printed board assemblies - Design and use - Part 5-5: Attachment (land/joint) considerations - C
Printed boards and printed board assemblies - Design and use - Part 5-6: Attachment (land/joint) considerations - C
Printed board and printed board assemblies - Design and use - Part 5-8: Attachment (land/joint) considerations - Ar
Circuit boards and circuit board assemblies - Design and use - Part 6-1: Land pattern design - Generic requirements
Circuit boards and circuit board assemblies - Design and use - Part 6-2: Land pattern design - Description of land pa
Printed boards and printed board assemblies - Design and use - Part 6-4: Land pattern design - Generic requiremen
Printed boards and printed board assemblies - Design and use - Part 7: Electronic component zero orientation for C
Circuit boards and circuit board assemblies - Design and use - Part 8: 3D shape data for CAD component library
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-
Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-6
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-
Test methods for electrical materials, circuit boards and other interconnection structures and assemblies - Part 2-7
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-
Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-8
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-
Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 5-5
Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 5-5
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 11
Attachment materials for electronic assembly - Part 1-1: Requirements for soldering fluxes for high-quality intercon

Attachment materials for electronic assembly - Part 1-2: Requirements for soldering pastes for high-quality interco
Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed
Printed board assemblies - Part 1: Generic specification - Requirements for soldered electrical and electronic assem
Printed board assemblies - Part 1: Generic specification - Requirements for soldered electrical and electronic assem
Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies
Corrigendum 1 - Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount solder
Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assembl
Printed board assemblies - Part 4: Sectional specification - Requirements for terminal soldered assemblies
Printed board assemblies - Part 6: Evaluation criteria for voids in soldered joints of BGA and LGA and measurement
Printed board assemblies - Part 7: Technical cleanliness of components and printed board assemblies
Printed board assemblies - Part 8: Voiding in solder joints of printed board assemblies for use in automotive electro
Printed board assemblies - Part 9: Electrochemical reliability and ionic contamination on printed circuit board asser
Printed board assemblies - Part 10: Application and utilization of protective coatings for electronic assemblies
Quality assessment systems - Part 1: Registration and analysis of defects on printed board assemblies
Quality assessment systems - Part 2: Selection and use of sampling plans for inspection of electronic components a
Quality assessment systems - Part 3: Selection and use of sampling plans for printed board and laminate end-produ
Materials for printed boards and other interconnecting structures - Part 2-1: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-2: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-4: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-5: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-6: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-7: Reinforced base materials clad and un
Materials for printed boards and other interconnecting structures - Part 2-8: Reinforced base materials clad and un
Materials for printed boards and other interconnecting structures - Part 2-9: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-10: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-11: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-12: Sectional specification set for reinfo
Materials for printed boards and other interconnecting structures - Part 2-13: Sectional specification set for reinfo
Materials for printed boards and other interconnecting structures - Part 2-21: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-22: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-23: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-26: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-27: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-30: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-31: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-32: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-33: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-34: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-35: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-36: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-37: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-38: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-39: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-40: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 2-41: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-42: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-43: Reinforced base materials clad and u

Materials for printed boards and other interconnecting structures - Part 2-44: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-45: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-46: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-47: Reinforced base materials clad and u
Materials for printed boards and other interconnecting structures - Part 2-51: Reinforced base materials, clad and u
Materials for printed boards and other interconnecting structures - Part 3-3: Sectional specification set for unreinfo
Materials for printed boards and other interconnecting structures - Part 3-4: Sectional specification set for unreinfo
Materials for printed boards and other interconnecting structures - Part 3-5: Sectional specification set for unreinfo
Materials for printed boards and other interconnecting structures - Part 4-1: Sectional specification set for prepreg
Materials for printed boards and other interconnecting structures - Part 4-2: Sectional specification set for prepreg
Materials for printed boards and other interconnecting structures - Part 4-5: Sectional specification set for prepreg
Materials for printed boards and other interconnecting structures - Part 4-11: Sectional specification set for prepre
Materials for printed boards and other interconnecting structures - Part 4-12: Sectional specification set for prepre
Materials for printed boards and other interconnecting structures - Part 4-14: Sectional specification set for prepre
Materials for printed boards and other interconnecting structures - Part 4-15: Sectional specification set for prepre
Materials for printed boards and other interconnecting structures - Part 4-16: Sectional specification set for prepre
Materials for printed boards and other interconnecting structures - Part 4-17: Sectional specification set for prepre
Materials for printed boards and other interconnecting structures - Part 4-18: Sectional specification set for prepre
Materials for printed boards and other interconnecting structures - Part 4-19: Sectional specification set for prepre
Materials for interconnection structures - Part 5: Sectional specification set for conductive foils and films with and
Materials for interconnection structures - Part 5: Sectional specification set for conductive foils and films with or w
Materials for printed boards and other interconnecting structures – Part 6-3: Sectional specification set for reinforc
Materials for interconnection structures - Part 7: Sectional specification set for restraining core materials - Section
Materials for interconnection structures - Part 8: Sectional specification set for non-conductive films and coatings -
Materials for interconnection structures - Part 8: Sectional specification set for non-conductive films and coatings -
Digital Test Interchange Format (DTIF)
Delay and power calculation standards - Part 1: Integrated Circuit (IC) Open Library Architecture (OLA)
Delay and power calculation standards - Part 3: Standard Delay Format (SDF) for the electronic design process
Delay and power calculation standards - Part 4: Design and Verification of Low-Power, Energy-Aware Electronic Sys
Corrigendum 1 - Delay and power calculation standards - Part 4: Design and Verification of Low-Power, Energy-Awa
Software Interface for Maintenance Information Collection and Analysis (SIMICA)
Software Interface for Maintenance Information Collection and Analysis (SIMICA): Exchanging Test Results and Ses
Software Interface for Maintenance Information Collection and Analysis (SIMICA) - Part 2: Exchanging Maintenanc
Automatic Test Markup Language (ATML) for Exchanging Automatic Test Equipment and Test Information via XML
Standard for automatic test markup language (ATML) instrument description
Standard for automatic test markup language (ATML) test configuration
Standard for automatic test markup language (ATML) test adapter description
Standard for automatic test markup language (ATML) test station description
Electronic design interchange format (EDIF) - Part 1: Version 3 0 0. (This publication is available in electronic HTML
Electronic design interchange format (EDIF) - Part 2: Version 4 0 0. (This publication is available in electronic HTML
Behavioural languages - Part 1-1: VHDL Language Reference Manual
Behavioural languages - Part 6: VHDL Analog and Mixed-Signal Extensions
Behavioural languages - Part 7: SystemC R Language Reference Manual
Behavioural languages - Part 8: Standard SystemC Analog/Mixed-Signal Extensions Language Reference Manual
Surface mounting technology - Part 1: Standard method for the specification of surface mounting components (SM
Surface mounting technology - Part 2: Transportation and storage conditions of surface mounting devices (SMD) -
Surface mounting technology - Part 2: Transportation and storage conditions of surface mounting devices (SMD) -

Surface mounting technology - Part 3: Standard method for the specification of components for through-hole reflo
Surface mounting technology - Part 3-1: Standard method for the specification of components for through hole ref
Surface mounting technology - Part 4: Classification, packaging, labelling and handling of moisture sensitive devices
Surface mounting technology - Part 4: Classification, packaging, labelling and handling of moisture sensitive devices
Amendment 1 - Surface mounting technology - Part 4: Classification, packaging, labelling and handling of moisture
Surface mounting technology - Part 5-1: Surface strain on circuit boards - Strain gauge measurement applied to chi
Design automation - Part 1: Standard test language for all systems - Common abbreviated test language for all syste
IP-XACT, Standard Structure for Packaging, Integrating, and Reusing IP within Tool Flows
Quality of Electronic and Software Intellectual Property Used in System and System on Chip (SoC) Designs
Product package labels for electronic components using bar code and two-dimensional symbologies
Surface mounting technology - Environmental and endurance test methods for surface mount solder joint - Part 1-
Surface mounting technology - Environmental and endurance test methods for surface mount solder joint - Part 1-
Surface mounting technology - Environmental and endurance test methods for surface mount solder joint - Part 1-
Surface mounting technology - Environmental and endurance test methods for surface mount solder joint - Part 1-
Surface mounting technology - Environmental and endurance test methods for surface mount solder joints - Part 1
Electronics assembly technology - Part 3: Selection guidance of environmental and endurance test methods for sold
Artificial Intelligence Exchange and Service Tie to All Test Environments (AI-ESTATE)
Printed boards - Part 4: Rigid multilayer printed boards with interlayer connections - Sectional specification
Printed boards - Part 4: Rigid multilayer printed boards with interlayer connections - Sectional specification - Sectio
Standard Test Interface Language (STIL) for Digital Test Vector Data
Standard for Extensions to Standard Test Interface Language (STIL) for Semiconductor Design Environments
Standard for Extensions to Standard Test Interface Language (STIL) for DC Level Specification
Standard Testability Method for Embedded Core-based Integrated Circuits
Standard for Signal and Test Definition
SystemVerilog - Unified Hardware Design, Specification, and Verification Language
SystemVerilog - Part 2: Universal Verification Methodology Language Reference Manual
Property Specification Language (PSL)
Mapping rules and exchange methods for heterogeneous electronic parts libraries - Part 1: Building an integrated s
Test method for erosion of wave soldering equipment using molten lead-free solder alloy - Part 1: Erosion test meth
Test method for erosion of wave soldering equipment using molten lead-free solder alloy - Part 2: Erosion test meth
Test method for erosion of wave soldering equipment using molten lead-free solder alloy - Part 3: Selection guidanc
Documentation on design automation subjects - The Bird's-eye View of Design Languages (BVDL)
Electrochemical migration in printed wiring boards and assemblies - Mechanisms and testing
Device embedding assembly technology - Part 1: Generic specification for device embedded substrates
Device embedded substrate - Part 1-1: Generic specification - Test methods
Device embedded substrate - Part 2-1: Guidelines - General description of technology
Device embedded substrate - Part 2-2: Guidelines - Electrical testing
Device embedded substrate - Part 2-3: Guidelines - Design guide
Device embedded substrate - Part 2-4: Guidelines - Test element groups (TEG)
Device embedding assembly technology - Part 2-5: Guidelines - Implementation of a 3D data format for device emb
Device embedding assembly technology - Part 2-7: Guidelines - Accelerated stress testing of passive embedded circ
Device embedding assembly technology - Part 2-8: Guidelines - Warpage control of active device embedded substra
Device embedding assembly technology - Part 2-9: Guidelines - Concept of JISSO level in the electronic assembly tec
Device embedding assembly technology - Part 2-10: Design specification for cavity substrate
Device embedding assembly technology - Part 2-602: Guideline for stacked electronic module - Evaluation method
Standard for the common test interface pin map configuration for high-density, single-tier electronics test requiren
Standard for receiver fixture interface

Flexible printed circuit boards (FPCBs) - Method of compensation of impedance variations
Flexible printed circuit boards (FPCBs) - Method to decrease signal loss by using noise suppression materials
Documentation on design automation subjects - Mathematical algorithm hardware description languages for syste
Format for LSI-Package-Board Interoperable design
Endurance test methods for die attach materials - Part 2: Temperature cycling test method for die attach materials
Test method for mechanical properties of flexible opto-electric circuit boards under thermal stress
Power Modeling to Enable System Level Analysis
Software-Hardware Interface for Multi-Many-Core
Fixed resistors for use in electronic equipment - Part 4-10: Blank detail specification: Power resistors with axial lead
Fixed resistors for use in electronic equipment - Part 9: Sectional specification: Fixed surface mount resistor netwo
Fixed resistors for use in electronic equipment - Part 9-1: Blank detail specification: Fixed surface mount resistor ne
Packaging of components for automatic handling - Part 1: Tape packaging of components with axial leads on contir
Packaging of components for automatic handling - Part 1: Tape packaging of components with axial leads on contir
Amendment 1 - Packaging of components for automatic handling - Part 1: Tape packaging of components with axia
Packaging of components for automatic handling - Part 2: Tape packaging of components with unidirectional leads
Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous
Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous
Packaging of components for automatic handling - Part 3-3: Packaging of surface mount components on continuou
Packaging of components for automatic handling - Part 3-4: Packaging of surface mount components on continuou
Corrigendum 1 - Packaging of components for automatic handling - Part 3-4: Packaging of surface mount compone
Packaging of components for automatic handling - Part 4: Stick magazines for electronic components encapsulated
Packaging of components for automatic handling - Part 5: Matrix trays
Packaging of components for automatic handling - Part 5: Matrix trays
Packaging of components for automatic handling - Part 6: Bulk case packaging for surface mounting components
Packaging of components for automatic handling - Part 6-1: Bulk case packaging for miniaturized surface mounting
Packaging of components for automatic handling - Part 7: Introduction of a bulk blister pack for miniaturized comp
Preferred diameters of wire terminations of capacitors and resistors
Fixed capacitors for use in electronic equipment - Part 1-1: Generic blank detail specification
Fixed capacitors for use in electronic equipment - Part 3: Sectional specification - Surface mount fixed tantalum ele
Fixed capacitors for use in electronic equipment - Part 3-1: Blank detail specification: Surface mount fixed tantalum
Fixed capacitors for use in electronic equipment - Part 4-2: Blank detail specification - Fixed aluminium electrolytic
Fixed capacitors for use in electronic equipment - Part 9-1: Blank detail specification: Fixed capacitors of ceramic di
Fixed capacitors for use in electronic equipment - Part 11-1: Blank detail specification - Fixed polyethylene terephth
Fixed capacitors for use in electronic equipment - Part 14-2: Blank detail specification - Fixed capacitors for electro
Fixed capacitors for use in electronic equipment. Part 15: Blankdetail specification: Fixed tantalum capacitors with
Fixed capacitors for use in electronic equipment. Part 15: Blank detail specification: Fixed tantalum capacitors with
Fixed capacitors for use in electronic equipment - Part 16: Sectional specification - Fixed metallized polypropylene f
Corrigendum 1 - Fixed capacitors for use in electronic equipment - Part 16: Sectional specification - Fixed metallized
Fixed capacitors for use in electronic equipment - Part 16-1: Blank detail specification: Fixed metallized polypropyle
Fixed capacitors for use in electronic equipment - Part 17: Sectional specification - Fixed metallized polypropylene f
Fixed capacitors for use in electronic equipment - Part 17: Sectional specification - Fixed metallized polypropylene f
Corrigendum 1 - Fixed capacitors for use in electronic equipment - Part 17: Sectional specification - Fixed metallized
Fixed capacitors for use in electronic equipment - Part 18: Sectional specification - Fixed aluminium electrolytic surf
Fixed capacitors for use in electronic equipment - Part 18-1: Blank detail specification - Fixed aluminium electrolytic
Fixed capacitors for use in electronic equipment - Part 18-2: Blank detail specification - Fixed aluminium electrolytic
Fixed capacitors for use in electronic equipment - Part 19: Sectional specification: Fixed metallized polyethylene ter
Fixed capacitors for use in electronic equipment - Part 20: Sectional specification - Fixed metallized polyphenylene s

Fixed capacitors for use in electronic equipment - Part 20: Sectional specification - Fixed metallized polyphenylene s
Fixed capacitors for use in electronic equipment - Part 21: Sectional specification - Fixed surface mount multilayer c
Fixed capacitors for use in electronic equipment - Part 21: Sectional specification - Fixed surface mount multilayer c
Fixed capacitors for use in electronic equipment - Part 21-1: Blank detail specification: Fixed surface mount multilay
Corrigendum 1 - Fixed capacitors for use in electronic equipment - Part 21-1: Blank detail specification: Fixed surfac
Fixed capacitors for use in electronic equipment - Part 22-1: Blank detail specification: Fixed surface mount multilay
Corrigendum 1 - Fixed capacitors for use in electronic equipment - Part 22-1: Blank detail specification: Fixed surfac
Fixed capacitors for use in electronic equipment - Part 23: Sectional specification - Fixed metallized polyethylene na
Fixed capacitors for use in electronic equipment - Part 23: Sectional specification - Fixed metallized polyethylene na
Fixed capacitors for use in electronic equipment - Part 24: Sectional specification - Fixed tantalum electrolytic surfa
Fixed capacitors for use in electronic equipment - Part 24: Sectional specification - Fixed tantalum electrolytic surfa
Fixed capacitors for use in electronic equipment - Part 24-1: Blank detail specification - Surface mount fixed tantalu
Fixed capacitors for use in electronic equipment - Part 25: Sectional specification - Fixed aluminium electrolytic surf
Fixed capacitors for use in electronic equipment - Part 25: Sectional specification - Fixed aluminium electrolytic surf
Corrigendum 1 - Fixed capacitors for use in electronic equipment - Part 25: Sectional specification - Fixed aluminiur
Fixed capacitors for use in electronic equipment - Part 25-1: Blank detail specification - Surface mount fixed alumin
Fixed capacitors for use in electronic equipment - Part 26: Sectional specification - Fixed aluminium electrolytic cap
Fixed capacitors for use in electronic equipment - Part 26: Sectional specification - Fixed aluminium electrolytic cap
Corrigendum 1 - Fixed capacitors for use in electronic equipment - Part 26: Sectional specification - Fixed aluminiur
Fixed capacitors for use in electronic equipment - Part 26-1: Blank detail specification - Fixed aluminium electrolytic
Potentiometers for use in electronic equipment - Part 3: Sectional specification: Rotary precision potentiometers
Potentiometers for use in electronic equipment - Part 4: Sectional specification: Single-turn rotary power potentior
Potentiometers for use in electronic equipment - Part 5: Sectional specification - Single-turn rotary low-power wire
Potentiometers for use in electronic equipment - Part 6: Sectional specification - Surface mount preset potentiome
Directly heated negative temperature coefficient thermistors - Part 1: Generic specification
Directly heated negative temperature coefficient thermistors - Part 2: Sectional specification - Surface mount negat
Directly heated negative temperature coefficient thermistors - Part 2: Sectional specification - Surface mount negat
Method for the determination of the space required by capacitors and resistors with unidirectional terminations
Thermistors - Directly heated positive step-function temperature coefficient - Part 1-2: Blank detail specification - H
Thermistors - Directly heated positive step-function temperature coefficient - Part 1-3: Blank detail specification - In
Thermistors - Directly heated positive step-function temperature coefficient - Part 1-4: Blank detail specification - S
Capacitors and resistors for use in electronic equipment - Preferred dimensions of shaft ends, bushes and for the m
Corrigendum 1 - Fixed capacitors for use in electronic equipment - Preferred dimensions of shaft ends, bushes and
Corrigendum 2 - Capacitors and resistors for use in electronic equipment - Preferred dimensions of shaft ends, bush
Fixed inductors for electromagnetic interference suppression - Part 2: Sectional specification on power line chokes
Fixed inductors for electromagnetic interference suppression - Part 2-1: Blank detail specification - Inductors for wl
Complete filter units for radio interference suppression - Part 2-1: Blank detail specification - Passive filter units for
Complete filter units for radio interference suppression - Part 2-2: Blank detail specification - Passive filter uits for e
Passive filter units for electromagnetic interference suppression - Part 3: Passive filter units for which safety tests a
Passive filter units for electromagnetic interference suppression - Part 3: Passive filter units for which safety tests a
Guidance information on the application of capacitors, resistors, inductors and complete filter units for electromag
Polymeric thermistors - Directly heated positive step function temperature coefficient - Part 1: Generic specificatio
Corrigendum 1 - Polymeric thermistors - Directly heated positive step function temperature coefficient - Part 1: Ge
Polymeric thermistors - Directly heated positive step function temperature coefficient - Part 1-1: Blank detail specif
Fixed electric double-layer capacitors for use in electric and electronic equipment - Part 1: Generic specification
Fixed electric double-layer capacitors for use in electronic equipment - Part 2: Sectional specfication - Electric doub
Fixed electric double-layer capacitors for use in electronic equipment - Part 2-1: Blank detail specification - Electric

ESL measuring method - Part 1: Capacitors with lead terminal for use in electronic equipment
ESL measuring method - Part 2: Surface mount capacitors for use in electronic equipment
Low resistance measurements - Methods and guidance
Corrigendum 1 - Low resistance measurements - Methods and guidance
Lithium ion capacitors for use in electric and electronic equipment - Test methods for electrical characteristics
Basic qualification of DC-link film capacitors for automotive use - General requirements, test conditions and tests
Application of fixed capacitors in electronic equipment - Part 1: Aluminium electrolytic capacitors
Semiconductor devices - Mechanical and climatic test methods - Part 1: General
Corrigendum 1 - Semiconductor devices - Mechanical and climatic test methods - Part 1: General
Semiconductor devices - Mechanical and climatic test methods - Part 2: Low air pressure
Corrigendum 1 - Semiconductor devices - Mechanical and climatic test methods - Part 2: Low air pressure
Semiconductor devices - Mechanical and climatic test methods - Part 3: External visual examination
Semiconductor devices - Mechanical and climatic test methods - Part 4: Damp heat, steady state, highly accelerate
Semiconductor devices - Mechanical and climatic test methods - Part 5: Steady-state temperature humidity bias lif
Semiconductor devices - Mechanical and climatic test methods - Part 5: Steady-state temperature humidity bias lif
Semiconductor devices - Mechanical and climatic test methods - Part 6: Storage at high temperature
Semiconductor devices - Mechanical and climatic test methods - Part 7: Internal moisture content measurement ar
Semiconductor devices - Mechanical and climatic test methods - Part 8: Sealing
Corrigendum 1 - Semiconductor devices - Mechanical and climatic test methods - Part 8: Sealing
Corrigendum 2 - Semiconductor devices - Mechanical and climatic test methods - Part 8: Sealing
Semiconductor devices - Mechanical and climatic test methods - Part 9: Permanence of marking
Semiconductor devices - Mechanical and climatic test methods - Part 10: Mechanical shock - device and subassemb
Semiconductor devices - Mechanical and climatic test methods - Part 11: Rapid change of temperature - Two-fluid-
Corrigendum 1 - Semiconductor devices - Mechanical and climatic test methods - Part 11: Rapid change of tempera
Corrigendum 2 - Semiconductor devices - Mechanical and climatic test methods - Part 11: Rapid change of tempera
Semiconductor devices - Mechanical and climatic test methods - Part 12: Vibration, variable frequency
Semiconductor devices - Mechanical and climatic test methods - Part 13: Salt atmosphere
Semiconductor devices - Mechanical and climatic test methods - Part 14: Robustness of terminations (lead integrity
Semiconductor devices - Mechanical and climatic test methods - Part 15: Resistance to soldering temperature for t
Semiconductor devices - Mechanical and climatic test methods - Part 15: Resistance to soldering temperature for t
Semiconductor devices - Mechanical and climatic test methods - Part 16: Particle impact noise detection (PIND)
Semiconductor devices - Mechanical and climatic test methods - Part 17: Neutron irradiation
Semiconductor devices - Mechanical and climatic test methods - Part 18: Ionizing radiation (total dose)
Semiconductor devices - Mechanical and climatic test methods - Part 18: Ionizing radiation (total dose)
Semiconductor devices - Mechanical and climatic test methods - Part 19: Die shear strength
Semiconductor devices - Mechanical and climatic test methods - Part 19: Die shear strength
Amendment 1 - Semiconductor devices - Mechanical and climatic test methods - Part 19: Die shear strength
Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs
Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs
Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shippin
Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shippin
Semiconductor devices - Mechanical and climatic test methods - Part 21: Solderability
Semiconductor devices - Mechanical and climatic test methods - Part 22: Bond strength
Corrigendum 1 - Semiconductor devices - Mechanical and climatic test methods - Part 22: Bond strength
Semiconductor devices - Mechanical and climatic test methods - Part 23: High temperature operating life
Semiconductor devices - Mechanical and climatic test methods - Part 23: High temperature operating life
Amendment 1 - Semiconductor devices - Mechanical and climatic test methods - Part 23: High temperature operat

Semiconductor devices - Mechanical and climatic test methods - Part 24: Accelerated moisture resistance - Unbias
Semiconductor devices - Mechanical and climatic test methods - Part 25: Temperature cycling
Semiconductor devices - Mechanical and climatic test methods - Part 26: Electrostatic discharge (ESD) sensitivity te
Semiconductor devices - Mechanical and climatic test methods - Part27: Electrostatic discharge (ESD) sensitivity te
Semiconductor devices - Mechanical and climatic test methods - Part 27: Electrostatic discharge (ESD) sensitivity te
Amendment 1 - Semiconductor devices - Mechanical and climatic test methods - Part 27: Electrostatic discharge (E
Semiconductor devices - Mechanical and climatic test methods - Part 28: Electrostatic discharge (ESD) sensitivity te
Semiconductor devices - Mechanical and climatic test methods - Part 28: Electrostatic discharge (ESD) sensitivity te
Semiconductor devices - Mechanical and climatic test methods - Part 29: Latch-up test
Semiconductor devices - Mechanical and climatic test methods - Part 30: Preconditioning of non-hermetic surface
Semiconductor devices - Mechanical and climatic test methods - Part 30: Preconditioning of non-hermetic surface
Semiconductor devices - Mechanical and climatic test methods - Part 31: Flammability of plastic-encapsulated devi
Corrigendum 1 - Semiconductor devices - Mechanical and climatic test methods - Part 31: Flammability of plastic-e
Semiconductor devices - Mechanical and climatic test methods - Part 32: Flammability of plastic-encapsulated devi
Semiconductor devices - Mechanical and climatic test methods - Part 32: Flammability of plastic-encapsulated devi
Corrigendum 1 - Semiconductor devices - Mechanical and climatic test methods - Part 32: Flammability of plastic-e
Amendment 1 - Semiconductor devices - Mechanical and climatic test methods - Part 32: Flammability of plastic-er
Semiconductor devices - Mechanical and climatic test methods - Part 33: Accelerated moisture resistance - Unbias
Semiconductor devices - Mechanical and climatic test methods - Part 34: Power cycling
Semiconductor devices - Mechanical and climatic test methods - Part 35: Acoustic microscopy for plastic encapsula
Semiconductor devices - Mechanical and climatic test methods - Part 36: Acceleration, steady state
Semiconductor devices - Mechanical and climatic test methods - Part 37: Board level drop test method using an ac
Semiconductor devices - Mechanical and climatic test methods - Part 37: Board level drop test method using an ac
Semiconductor devices - Mechanical and climatic test methods - Part 38: Soft error test method for semiconductor
Semiconductor devices - Mechanical and climatic test methods - Part 39: Measurement of moisture diffusivity and
Semiconductor devices - Mechanical and climatic test methods - Part 39: Measurement of moisture diffusivity and
Semiconductor devices - Mechanical and climatic test methods - Part 40: Board level drop test method using a stra
Semiconductor devices - Mechanical and climatic test methods - Part 41: Standard reliability testing methods of no
Semiconductor devices - Mechanical and climatic test methods - Part 42: Temperature and humidity storage
Semiconductor devices - Mechanical and climatic test methods - Part 44: Neutron beam irradiated single event effe
Semiconductor devices - Micro-electromechanical devices - Part 28: Performance testing method of vibration-drive
Semiconductor die products - Part 1: Procurement and use
Semiconductor die products - Part 2: Exchange data formats
Semiconductor die products - Part 3: Recommendations for good practice in handling, packing and storage
Semiconductor die products - Part 4: Questionnaire for die users and suppliers
Semiconductor die products - Part 5: Requirements for information concerning electrical simulation
Semiconductor die products - Part 6: Requirements for information concerning thermal simulation
Semiconductor die products - Part 7: XML schema for data exchange
Semiconductor die products - Part 8: EXPRESS model schema for data exchange
Bias-temperature stability test for metal-oxide, semiconductor, field-effect transistors (MOSFET)
Semiconductor devices - Bias-temperature stability test for metal-oxide, semiconductor, field-effect transistors (M
Semiconductor devices - Time dependent dielectric breakdown (TDDB) test for gate dielectric films
Semiconductor devices - Part 1: Time-dependent dielectric breakdown (TDDB) test for inter-metal layers
Semiconductor devices - Constant current electromigration test
Semiconductor devices - Hot carrier test on MOS transistors
Semiconductor devices - Mobile ion tests for metal-oxide semiconductor field effect transistors (MOSFETs)
Semiconductor devices - Metallization stress void test

Electronic components - Long-term storage of electronic semiconductor devices - Part 1: General
Electronic components - Long-term storage of electronic semiconductor devices - Part 2: Deterioration mechanism
Electronic components - Long-term storage of electronic semiconductor devices - Part 3: Data
Electronic components - Long-term storage of electronic semiconductor devices - Part 4: Storage
Electronic components - Long-term storage of electronic semiconductor devices - Part 5: Die and wafer devices
Electronic components - Long-term storage of electronic semiconductor devices - Part 6: Packaged or finished devi
Electronic components - Long-term storage of electronic semiconductor devices - Part 7: Micro-electromechanical
Electronic components - Long-term storage of electronic semiconductor devices - Part 8: Passive electronic devices
Electronic components - Long-term storage of electronic semiconductor devices - Part 9: Special cases
Environmental acceptance requirements for tin whisker susceptibility of tin and tin alloy surface finishes on semico
Electrostatic discharge sensitivity testing - Transmission line pulse (TLP) - Component level
Semiconductor devices - Semiconductor interface for human body communication - Part 1: General requirements
Semiconductor devices - Semiconductor interface for human body communication - Part 2: Characterization of inte
Semiconductor devices - Semiconductor interface for human body communication - Part 3: Functional type and its
Semiconductor devices - Semiconductor interface for human body communication - Part 4: Capsule endoscope
Semiconductor devices - Semiconductor devices for energy harvesting and generation - Part 1: Vibration based piez
Semiconductor devices - Semiconductor devices for energy harvesting and generation - Part 2: Thermo power base
Semiconductor devices - Semiconductor devices for energy harvesting and generation - Part 3: Vibration based elec
Semiconductor devices - Semiconductor devices for energy harvesting and generation - Part 4: Test and evaluation
Semiconductor devices - Semiconductor devices for energy harvesting and generation - Part 5: Test method for me
Semiconductor devices - Semiconductor devices for energy harvesting and generation - Part 6: Test and evaluation
Semiconductor devices - Semiconductor devices for energy harvesting and generation - Part 7: Linear sliding mode
Semiconductor devices - Semiconductor devices for energy harvesting and generation - Part 8: Test and evaluation
Semiconductor devices - Stress migration test standard - Part 1: Copper stress migration test standard
Semiconductor devices - Flexible and stretchable semiconductor devices - Part 1: Bending test method for conduct
Semiconductor devices - Flexible and stretchable semiconductor devices - Part 2: Evaluation method for electron m
Semiconductor devices - Flexible and stretchable semiconductor devices - Part 3: Evaluation of thin film transistor c
Semiconductor devices - Flexible and stretchable semiconductor devices - Part 4: Fatigue evaluation for flexible cor
Semiconductor devices - Flexible and stretchable semiconductor devices - Part 5: Test method for thermal characte
Semiconductor devices - Flexible and stretchable semiconductor devices - Part 6: Test method for sheet resistance
Semiconductor devices - Flexible and stretchable semiconductor devices - Part 7: Test method for characterizing th
Semiconductor devices - Flexible and stretchable semiconductor devices - Part 8: Test method for stretchability, fle
Semiconductor devices - Flexible and stretchable semiconductor devices - Part 9: Performance testing methods of c
Semiconductor devices - Semiconductor interface for automotive vehicles - Part 1: General requirements of power
Semiconductor devices - Semiconductor interface for automotive vehicles - Part 2: Efficiency evaluation methods o
Semiconductor devices - Semiconductor interface for automotive vehicles - Part 3: Shock driven piezoelectric energ
Semiconductor devices - Semiconductor interface for automotive vehicles - Part 4: Evaluation method of data inter
Semiconductor devices - Non-destructive recognition criteria of defects in silicon carbide homoepitaxial wafer for p
Semiconductor devices - Non-destructive recognition criteria of defects in silicon carbide homoepitaxial wafer for p
Semiconductor devices - Non-destructive recognition criteria of defects in silicon carbide homoepitaxial wafer for p
Semiconductor devices - Non-destructive recognition criteria of defects in silicon carbide homoepitaxial wafer for p
Semiconductor devices - Scan based ageing level estimation for semiconductor devices
Semiconductor devices - Measurement and evaluation methods of kinetic energy harvesting devices under practica
Semiconductor devices - Classification of defects in gallium nitride epitaxial film on silicon carbide substrate
Semiconductor devices - Semiconductor devices for wireless power transfer and charging - Part 1: General requirer
Semiconductor devices - Reliability test method for silicon carbide discrete metal-oxide semiconductor field effect t
Semiconductor devices - Reliability test method for silicon carbide discrete metal-oxide semiconductor field effect t

Semiconductor devices - Reliability test method by inductive load switching for gallium nitride transistors
Semiconductor devices - Generic semiconductor qualification guidelines - Part 1: Guidelines for IC reliability qualific
Semiconductor devices - Guidelines for reliability qualification plans - Part 2: Concept of mission profile
Semiconductor devices - Standardization roadmap of fault test method for automotive vehicles
Semiconductor devices - Semiconductor devices for IoT system - Part 1: Test method of sound variation detection
Dynamic on-resistance test method guidelines for GaN HEMT based power conversion devices
Semiconductor devices - Micro-electromechanical devices - Part 1: Terms and definitions
Semiconductor devices - Micro-electromechanical devices - Part 2: Tensile testing method of thin film materials
Semiconductor devices - Micro-electromechanical devices - Part 3: Thin film standard test piece for tensile testing
Semiconductor devices - Micro-electromechanical devices - Part 4: Generic specification for MEMS
Semiconductor devices - Micro-electromechanical devices - Part 5: RF MEMS switches
Corrigendum 1 - Semiconductor devices - Micro-electromechanical devices - Part 5: RF MEMS switches
Semiconductor devices - Micro-electromechanical devices - Part 6: Axial fatigue testing methods of thin film materi
Semiconductor devices - Micro-electromechanical devices - Part 7: MEMS BAW filter and duplexer for radio freque
Semiconductor devices - Micro-electromechanical devices - Part 8: Strip bending test method for tensile property n
Semiconductor devices - Micro-electromechanical devices - Part 9: Wafer to wafer bonding strength measurement
Corrigendum 1 - Semiconductor devices - Micro-electromechanical devices - Part 9: Wafer to wafer bonding streng
Semiconductor devices - Micro-electromechanical devices - Part 10: Micro-pillar compression test for MEMS mater
Corrigendum 1 - Semiconductor devices - Micro-electromechanical devices - Part 10: Micro-pillar compression test
Semiconductor devices - Micro-electromechanical devices - Part 11: Test method for coefficients of linear thermal e
Semiconductor devices - Micro-electromechanical devices - Part 12: Bending fatigue testing method of thin film ma
Semiconductor devices - Micro-electromechanical devices - Part 13: Bend - and shear - type test methods of measu
Semiconductor devices - Micro-electromechanical devices - Part 14: Forming limit measuring method of metallic fil
Semiconductor devices - Micro-electromechanical devices - Part 16: Test methods for determining residual stresses
Semiconductor devices - Micro-electromechanical devices - Part 17: Bulge test method for measuring mechanical p
Semiconductor devices - Micro-electromechanical devices - Part 18: Bend testing methods of thin film materials
Semiconductor devices - Micro-electromechanical devices - Part 19: Electronic compasses
Semiconductor devices - Micro-electromechanical devices - Part 20: Gyroscopes
Semiconductor devices - Micro-electromechanical devices - Part 21: Test method for Poisson's ratio of thin film ME
Semiconductor devices - Micro-electromechanical devices - Part 22: Electromechanical tensile test method for con
Semiconductor devices - Micro-electromechanical devices - Part 25: Silicon based MEMS fabrication technology - M
Semiconductor devices - Micro-electromechanical devices - Part 26: Description and measurement methods for mi
Semiconductor devices - Micro-electromechanical devices - Part 27: Bond strength test for glass frit bonded structu
Semiconductor devices - Micro-electromechanical devices - Part 29: Electromechanical relaxation test method for f
Semiconductor devices - Micro-electromechanical devices - Part 30: Measurement methods of electro-mechanical
Semiconductor devices - Micro-electromechanical devices - Part 31: Four-point bending test method for interfacial
Semiconductor devices - Micro-electromechanical devices - Part 32: Test method for the nonlinear vibration of MEI
Semiconductor devices - Micro-electromechanical devices - Part 33: MEMS piezoresistive pressure-sensitive device
Semiconductor devices - Micro-electromechanical devices - Part 34: Test methods for MEMS piezoresistive pressur
Semiconductor devices - Micro-electromechanical devices - Part 35: Test method of electrical characteristics under
Semiconductor devices - Micro-electromechanical devices - Part 36: Environmental and dielectric withstand test m
Semiconductor devices - Micro-electromechanical devices - Part 37: Environmental test methods of MEMS piezoele
Semiconductor devices - Micro-electromechanical devices - Part 38: Test method for adhesion strength of metal pc
Semiconductor devices - Micro-electromechanical devices - Part 40:Test methods of micro-electromechanical inert
Semiconductor devices - Micro-electromechanical devices - Part 41: RF MEMS circulators and isolators
Semiconductor devices - Micro-electromechanical devices - Part 42: Measurement methods of electro-mechanical
Semiconductor devices - Micro-electromechanical devices - Part 43: Test method of electrical characteristics after c

Semiconductor devices - Micro-electromechanical devices - Part 44: Test methods for dynamic performances of MI
Semiconductor devices - Micro-electromechanical devices - Part 47: Silicon based MEMS fabrication technology - M
Semiconductor devices - Micro-electromechanical devices - Part 48: Test method for determining solution concent
Semiconductor devices - Discrete devices - Part 4: Microwave diodes and transistors
Semiconductor devices - Discrete devices - Part 4: Microwave diodes and transistors
Amendment 1 - Semiconductor devices - Discrete devices - Part 4: Microwave diodes and transistors
Semiconductor devices - Part 5-4: Optoelectronic devices - Semiconductor lasers
Semiconductor devices - Part 5-5: Optoelectronic devices - Photocouplers
Semiconductor devices - Part 5-6: Optoelectronic devices - Light emitting diodes
Semiconductor devices - Part 5-6: Optoelectronic devices - Light emitting diodes
Semiconductor devices - Part 5-7: Optoelectronic devices - Photodiodes and phototransistors
Semiconductor devices - Part 5-8: Optoelectronic devices - Light emitting diodes - Test method of optoelectronic ef
Semiconductor devices - Part 5-9: Optoelectronic devices - Light emitting diodes - Test method of the internal quan
Semiconductor devices - Part 5-10: Optoelectronic devices - Light emitting diodes - Test method of the internal qua
Semiconductor devices - Part 5-11: Optoelectronic devices - Light emitting diodes - Test method of radiative and nc
Semiconductor devices - Part 5-12: Optoelectronic devices - Light emitting diodes - Test method of LED efficiencies
Semiconductor devices - Part 5-13: Optoelectronic devices - Hydrogen sulphide corrosion test for LED packages
Semiconductor devices - Part 5-14: Optoelectronic devices - Light emitting diodes - Test method of the surface tem
Semiconductor devices - Part 5-15: Optoelectronic devices - Light emitting diodes - Test method of the flat-band vo
Semiconductor devices - Part 5-16: Optoelectronic devices - Light emitting diodes - Test method of the flat-band vo
Semiconductor devices - Part 6: Discrete devices - Thyristors
Semiconductor devices - Part 9: Discrete devices - Insulated-gate bipolar transistors (IGBTs)
Semiconductor devices - Part 14-1: Semiconductor sensors - Generic specification for sensors
Semiconductor devices - Part 14-2: Semiconductor sensors - Hall elements
Semiconductor devices - Part 14-3: Semiconductor sensors - Pressure sensors
Semiconductor devices - Discrete devices - Part 14-4: Semiconductor accelerometers
Semiconductor devices - Part 14-5: Semiconductor sensors - PN-junction semiconductor temperature sensor
Semiconductor devices - Part 14-10: Semiconductor sensors - Performance evaluation methods for wearable gluco
Semiconductor devices - Part 14-11: Semiconductor sensors - Test method of surface acoustic wave-based integrat
Semiconductor devices - Discrete devices - Part 15: Isolated power semiconductor devices
Semiconductor devices - Part 16-1: Microwave integrated circuits - Amplifiers
Semiconductor devices - Part 16-1: Microwave integrated circuits - Amplifiers
Semiconductor devices - Part 16-1: Microwave integrated circuits - Amplifiers
Amendment 1 - Semiconductor devices - Part 16-1: Microwave integrated circuits - Amplifiers
Amendment 2 - Semiconductor devices - Part 16-1: Microwave integrated circuits - Amplifiers
Semiconductor devices - Part 16-2: Microwave integrated circuits - Frequency prescalers
Semiconductor devices - Part 16-2: Microwave integrated circuits - Frequency prescalers
Amendment 1 - Semiconductor devices - Part 16-2: Microwave integrated circuits - Frequency prescalers
Semiconductor devices - Part 16-3: Microwave integrated circuits - Frequency converters
Semiconductor devices - Part 16-3: Microwave integrated circuits - Frequency converters
Semiconductor devices - Part 16-3: Microwave integrated circuits - Frequency converters
Amendment 1 - Semiconductor devices - Part 16-3: Microwave integrated circuits - Frequency converters
Amendment 2 - Semiconductor devices - Part 16-3: Microwave integrated circuits - Frequency converters
Semiconductor devices - Part 16-4: Microwave integrated circuits - Switches
Semiconductor devices - Part 16-4: Microwave integrated circuits - Switches
Semiconductor devices - Part 16-4: Microwave integrated circuits - Switches
Amendment 1 - Semiconductor devices - Part 16-4: Microwave integrated circuits - Switches

Amendment 2 - Semiconductor devices - Part 16-4: Microwave integrated circuits - Switches
Semiconductor devices - Part 16-5: Microwave integrated circuits - Oscillators
Semiconductor devices - Part 16-5: Microwave integrated circuits - Oscillators
Amendment 1 - Semiconductor devices - Part 16-5: Microwave integrated circuits - Oscillators
Corrigendum 1 - Semiconductor devices - Part 16-5: Microwave integrated circuits - Oscillators
Semiconductor devices - Part 16-6: Microwave integrated circuits - Frequency multipliers
Semiconductor devices - Part 16-7: Microwave integrated circuits - Attenuators
Semiconductor devices - Part 16-8: Microwave integrated circuits - Limiters
Semiconductor devices - Part 16-9: Microwave integrated circuits - Phase shifters
Semiconductor devices - Part 16-10: Technology Approval Schedule (TAS) for monolithic microwave integrated circ
Semiconductor devices - Part 17: Magnetic and capacitive coupler for basic and reinforced insulation
Corrigendum 1 - Semiconductor devices - Part 17: Magnetic and capacitive coupler for basic and reinforced insulati
Semiconductor devices - Part 18-1: Semiconductor bio sensors - Test method and data analysis for calibration of le
Semiconductor devices - Part 18-2: Semiconductor bio sensors - Evaluation process of lens-free CMOS photonic arr
Semiconductor devices - Part 18-3: Semiconductor bio sensors - Fluid flow characteristics of lens-free CMOS photo
Semiconductor devices - Part 18-4: Semiconductor bio sensors - Evaluation method of noise characteristics of lens-
Semiconductor devices - Part 18-5: Semiconductor bio sensors - Evaluation method for light responsivity characteri
Semiconductor devices - Part 19-1: Smart sensors - Control scheme of smart sensors
Semiconductor devices - Part 19-2: Smart sensors - Indication of specifications of sensors and power supplies to dri
Mechanical standardization of semiconductor devices - Part 2: Dimensions
Mechanical standardization of semiconductor devices. Part 2: Dimensions
Amendment 1 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 2 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 3 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 4 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 5 - Mechanical standardization of semiconductor devices. Part 2: Dimensions
Amendment 6 - Mechanical standardization of semiconductor devices. Part 2: Dimensions
Amendment 7 - Mechanical standardization of semiconductor devices. Part 2: Dimensions
Amendment 8 - Mechanical standardization of semiconductor devices. Part 2: Dimensions
Amendment 9 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 10 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 11 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 12 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 13 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 14 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 15 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 16 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 17 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 18 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 19 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 20 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Amendment 21 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Mechanical standardization of semiconductor devices - Part 3: General rules for the preparation of outline drawing
Mechanical standardization of semiconductor devices - Part 4: Coding system and classification into forms of packa
Mechanical standardization of semiconductor devices - Part 4: Coding system and classification into forms of packa
Amendment 1 - Mechanical standardization of semiconductor devices - Part 4: Coding system and classification int
Mechanical standardization of semiconductor devices - Part 5: Recommendations applying to integrated circuit pac

Mechanical standardization of semiconductor devices - Part 6: General rules for the preparation of outline drawing
Mechanical standardization of semiconductor devices - Part 6-1: General rules for the preparation of outline drawi
Mechanical standardization of semiconductor devices - Part 6-2: General rules for the preparation of outline drawi
Corrigendum 1 - Mechanical standardization of semiconductor devices - Part 6-2: General rules for the preparation
Mechanical standardization of semiconductor devices - Part 6-3: General rules for the preparation of outline drawi
Mechanical standardization of semiconductor devices - Part 6-4: General rules for the preparation of outline drawi
Mechanical standardization of semiconductor devices - Part 6-5: General rules for the preparation of outline drawi
Mechanical standardization of semiconductor devices - Part 6-6: General rules for the preparation of outline drawi
Mechanical standardization of semiconductor devices - Part 6-8: General rules for the preparation of outline drawi
Mechanical standardization of semiconductor devices - Part 6-10: General rules for the preparation of outline draw
Mechanical standardization of semiconductor devices - Part 6-12: General rules for the preparation of outline draw
Mechanical standardization of semiconductor devices - Part 6-13: Design guideline of open-top-type sockets for Fir
Mechanical standardization of semiconductor devices - Part 6-16: Glossary of semiconductor tests and burn-in soc
Mechanical standardization of semiconductor devices - Part 6-17: General rules for the preparation of outline draw
Mechanical standardization of semiconductor devices - Part 6-18: General rules for the preparation of outline draw
Corrigendum 1 - Mechanical stardardization of semiconductor devices - Part 6-18: General rules for the preparatio
Corrigendum 2 - Mechanical standardization of semiconductor devices - Part 6-18: General rules for the preparatio
Mechanical standardization of semiconductor devices - Part 6-19: Measurement methods of the package warpage
Mechanical standardization of semiconductor devices - Part 6-20: General rules for the preparation of outline draw
Mechanical standardization of semiconductor devices - Part 6-21: General rules for the preparation of outline draw
Mechanical standardization of semiconductor devices - Part 6-22: General rules for the preparation of outline draw
Eighteenth supplement
Nineteenth supplement
Twentieth supplement
Twenty-first supplement
Mechanical standardization of semiconductor devices - Part 2: Dimensions
Corrigendum 1 - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Twenty-third supplement - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Twenty-fourth supplement - Mechanical standardization of semiconductor devices - Part 2: Dimensions
Thermal standardization on semiconductor packages - Part 1: Thermal resistance and thermal parameter of BGA, C
Semiconductor devices. Integrated circuits - Part 2: Digital integrated circuits - Section two: Family specification for
Amendment 1 - Semiconductor devices. Integrated circuits - Part 2: Digital integrated circuits - Section two: Family
Semiconductor devices - Integrated circuits - Part 2: Digital integrated circuits - Section five: Blank detail specificati
Semiconductor devices. Integrated circuits - Part 2: Digital integrated circuits - Section Six: Blank detail specificatio
Semiconductor devices. Integrated circuits - Part 2: Digital integrated circuits - Section seven: Blank detail specifica
Semiconductor devices - Integrated circuits - Part 2: Digital integrated circuits - Section Eight: Blank detail specifica
Semiconductor devices - Integrated circuits - Part 2: Digital integrated circuits - Section 9: Blank detail specification
Semiconductor devices - Integrated circuits - Part 2: Digital integrated circuits - Section 10: Blank detail specificatio
Semiconductor devices - Integrated circuits - Part 2-11: Digital integrated circuits - Blank detail specification for sin
Semiconductor devices - Integrated circuits - part2-12: Digital integrated circuits - Blank detail specification for pro
Semiconductor devices - Integrated circuits - Part 2-20: Digital integrated circuits - Family specification - Low voltag
Semiconductor devices - Integrated circuits - Part 4: Interface integrated circuits
Semiconductor devices - Integrated circuits - Part 4: Interface integrated circuits - Section 1: Blank detail specificati
Semiconductor devices - Integrated circuits - Part 4: Interface integrated circuits - Section 2: Blank detail specificati
Semiconductor devices - Integrated circuits - Part 4-3: Interface integrated circuits - Dynamic criteria for analogue-
Semiconductor devices - Integrated circuits - Part 5: Semicustom integrated circuits
Semiconductor devices - Integrated circuits - Part 11: Sectional specification for semiconductor integrated circuits

Amendment 1 - Semiconductor devices - Integrated circuits - Part 11: Sectional specification for semiconductor int
Amendment 2 - Semiconductor devices - Integrated circuits - Part 11: Sectional specification for semiconductor int
Semiconductor devices - Integrated circuits - Part 11-1: Internal visual examination for semiconductor integrated ci
Semiconductor devices - Integrated circuits - Part 20: Generic specification for film integrated circuits and hybrid fil
Semiconductor devices - Integrated circuits - Part 23-1: Hybrid integrated circuits and film structures - Manufacturi
Semiconductor devices - Integrated circuits - Part 23-2: Hybrid integrated circuits and film structures - Manufacturi
Semiconductor devices - Integrated circuits - Part 23-3: Hybrid integrated circuits and film structures - Manufacturi
Semiconductor devices - Integrated circuits - Part 23-4: Hybrid integrated circuits and film structures - Manufacturi
Semiconductor devices - Integrated circuits, Part 23-5: Hybrid integrated circuits and film structures - Manufacturi
Integrated circuits - Part 1: Procedures for manufacturing line approval and quality management
Integrated circuits - Manufacturing line approval application guideline
Integrated circuits - Manufacturing line approval - Demonstration vehicles
Interated circuits - Manufacturing line approval - Methodology for technology and failure analysis
Integrated circuits - Memory devices pin configurations
Integrated circuits - Measurement of electromagnetic emissions - Part 1: General conditions and definitions
Integrated circuits - Measurement of electromagnetic emissions - Part 1: General conditions and definitions
Integrated circuits - Measurement of electromagnetic emissions - Part 1-1: General conditions and definitions - Nea
Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 2: Measurement of radiat
Integrated circuits - Measurement of electromagnetic emissions - Part 3: Measurement of radiated emissions - Surf
Integrated circuits - Measurement of electromagnetic emissions - Part 4: Measurement of conducted emissions - 1
Integrated circuits - Measurement of electromagnetic emissions - Part 4: Measurement of conducted emissions - 1
Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 4-1: Measurement of con
Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 5: Measurement of condu
Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 6: Measurement of condu
Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 6: Measurement of condu
Corrigendum 1 - Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 6: Measu
Amendment 1 - Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 6: Measu
Integrated circuits - Measurement of electromagnetic emissions - Part 8: Measurement of radiated emissions - IC st
Integrated circuits - Measurement of electromagnetic emissions - Part 8: Measurement of radiated emissions - IC st
Integrated circuits - Measurement of electromagnetic immunity - Part 1: General conditions and definitions
Integrated circuits - Measurement of electromagnetic immunity - Part 2: Measurement of radiated immunity - TEM
Integrated circuits - Measurement of electromagnetic immunity 150 kHz to 1 GHz - Part 4: Direct RF power injectio
Integrated circuits - Measurement of electromagnetic immunity, 150 kHz to 1 GHz - Part 5: Workbench Faraday cag
Integrated circuits - Measurement of electromagnetic immunity - Part 8: Measurement of radiated immunity - IC st
Integrated circuits - Measurement of electromagnetic immunity - Part 9: Measurement of radiated immunity - Surf
Integrated circuits - Measurement of impulse immunity - Part 2: Synchronous transient injection method
Integrated circuits - Measurement of impulse immunity - Part 3: Non-synchronous transient injection method
Integrated circuits - EMC evaluation of transceivers - Part 1: General conditions and definitions
Integrated circuits - EMC evaluation of transceivers - Part 2: LIN transceivers
Integrated circuits - EMC evaluation of transceivers - Part 3: CAN transceivers
Corrigendum 1 - Integrated circuits - EMC evaluation of transceivers - Part 3: CAN transceivers
Integrated circuits - EMC evaluation of transceivers - Part 5: Ethernet transceivers
Integrated circuit - EMC evaluation of transceivers - Part 6: PSI5 transceivers
Integrated circuits - EMC evaluation of transceivers - Part 7: CXPI transceivers
Logic digital integrated circuits - Specification for I/O interface model for integrated circuit (IMIC version 1.3)
EMC IC modelling - Part 1: General modelling framework
Corrigendum 1 - EMC IC modelling - Part 1: General modelling framework

EMC IC modelling - Part 2: Models of integrated circuits for EMI behavioural simulation - Conducted emissions mod
EMC IC modelling - Part 2-1: Theory of black box modelling for conducted emission
EMC IC modelling - Part 3: Models of integrated circuits for EMI behavioural simulation - Radiated emissions model
EMC IC modelling - Part 4: Models of integrated circuits for RF immunity behavioural simulation - Conducted immu
EMC IC modelling - Part 6: Models of integrated circuits for pulse immunity behavioural simulation - Conducted pul
Integrated circuits - Three dimensional integrated circuits - Part 1: Terminology
Integrated circuits - Three dimensional integrated circuits - Part 2: Alignment of stacked dies having fine pitch inter
Integrated circuits - Three dimensional integrated circuits - Part 3: Model and measurement conditions of through-

TC	Technical committee Name
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology

TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology

TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology

TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology

TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 91	Electronics assembly technology
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment

TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment

TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 40	Capacitors and resistors for electronic equipment
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices

TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices

TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices

TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
TC 47	Semiconductor devices
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems

SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47F	Micro-electromechanical systems
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices

SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47E	Discrete semiconductor devices
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging

SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47D	Semiconductor devices packaging
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits

SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits
SC 47A	Integrated circuits

SC 47A Integrated circuits
SC 47A Integrated circuits
SC 47A Integrated circuits
SC 47A Integrated circuits
SC 47A Integrated circuits
SC 47A Integrated circuits
SC 47A Integrated circuits
SC 47A Integrated circuits